P-Ch 60V Fast Switching MOSFETs

Features

- Split Gate Trench MOSFET technology
- Excellent package for heat dissipation
- High density cell design for low $R_{DS(ON)}$

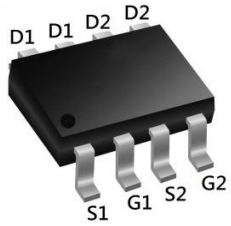
Product Summery

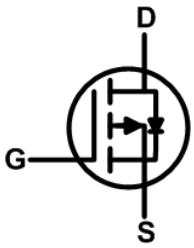
BVDSS	RDSON	ID
-60V	42mΩ	-10A

Applications

- DC-DC Converters
- Power management functions
- Synchronous-rectification applications

SOP8 Pin Configuration





Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-60	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V[1,6]	-10	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V[1,6]	-5	A
I_{DM}	Pulsed Drain Current[2]	-40	A
EAS	Single Pulse Avalanche Energy[3]	48	mJ
I_{AS}	Avalanche Current	---	A
P_D@T_C=25℃	Total Power Dissipation[4]	40	W
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1]	---	---	℃/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	---	3.12	℃/W

Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=-250uA	-100	---	---	V
$\triangle BV_{DSS}/\triangle T_J$	BV_{DSS} Temperature Coefficient	Reference to 25℃ , I_D=1mA	---	---	---	V/℃
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=-10V , I_D=-4A	---	42	54	mΩ
		V_{GS}=-4.5V , I_D=-2A	---	54	77	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =-250uA	-1.3	-1.8	-2.3	V
$\triangle V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	---	---	mV/℃
I_{DSS}	Drain-Source Leakage Current	V_{DS}=-60V , V_{GS}=0V , T_J=25℃	---	---	1	uA
		V_{DS}=-60V, V_{GS}=0V , T_J=100℃	---	---	---	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
gfs	Forward Transconductance	V_{DS}=-5V , I_D=-6A	---	---	---	S
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	5	---	Ω
Q_g	Total Gate Charge	V_{DS}=-30V , V_{GS}=-10V , I_D=-4A	---	11.6	---	nC
Q_{gs}	Gate-Source Charge		---	2.4	---	
Q_{gd}	Gate-Drain Charge		---	1.5	---	
$T_{d(on)}$	Turn-On Delay Time	VGS=-10V, VDD=-30V, RG=3Ω, ID=-4A	---	10	---	ns
T_r	Rise Time		---	6	---	
$T_{d(off)}$	Turn-Off Delay Time		---	40	---	
T_f	Fall Time		---	13	---	
C_{iss}	Input Capacitance	V_{DS}=-30V , V_{GS}=0V , f=1MHz	---	667	---	pF
C_{oss}	Output Capacitance		---	114	---	
C_{rss}	Reverse Transfer Capacitance		---	5.2	---	

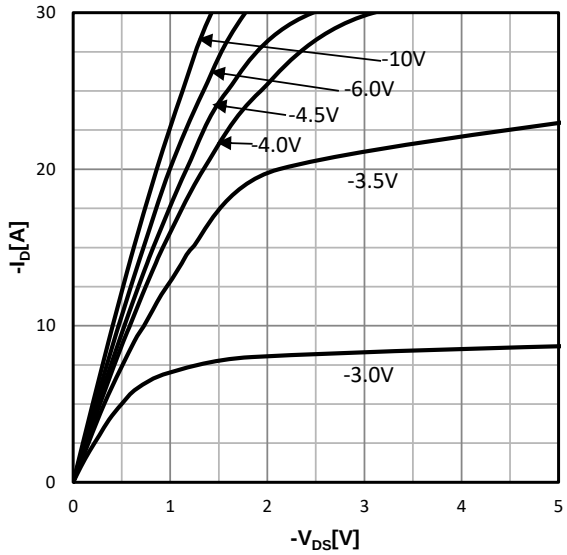
Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current[1,4]	V_G=V_D=0V , Force Current	---	---	-10	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=-4A , T_J=25℃	---	---	-1.2	V
t_{rr}	Reverse Recovery Time	IF=-4A , di/dt=100A/μs , T_J=25℃, VDD=-30V	---	28	---	nS
Q_{rr}	Reverse Recovery Charge		---	40	---	nC

a1：Repetitive rating; pulse width limited by maximum junction temperature a2：V_{DD}=-30V,L=0.3mH, R_G=25Ω, Starting T_j=25°C

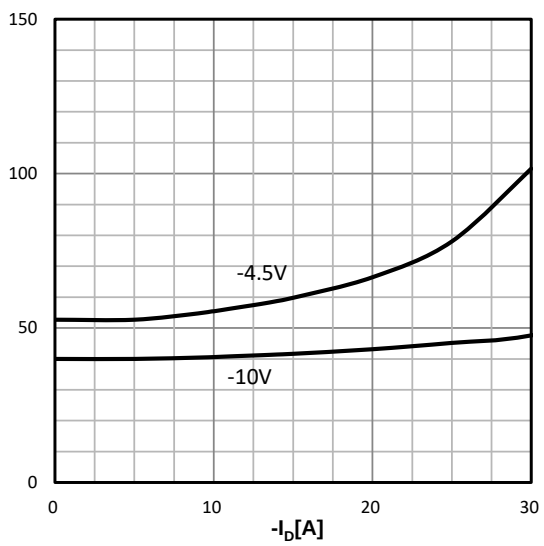
General Description：

Figure 1: Typ. output characteristics



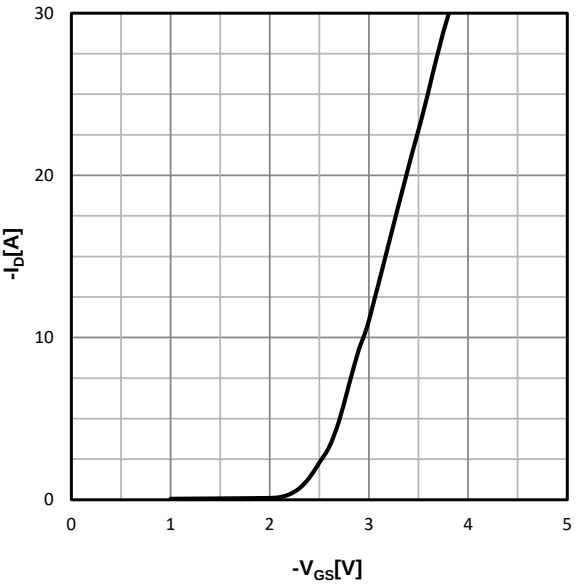
$I_D=f(V_{DS})$, T_j=25 °C; parameter: V_{GS}

Figure 2: Typ. drain-source on resistance



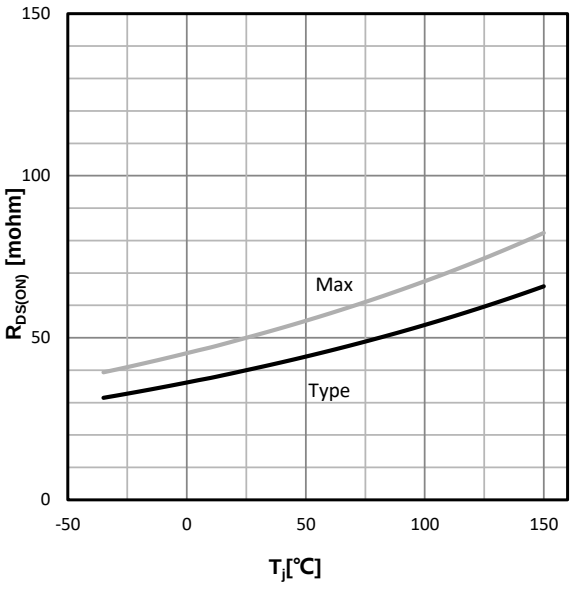
$R_{DS(on)}=f(I_D)$, T_j=25 °C; parameter: V_{GS}

Figure 3: Typ. transfer characteristics



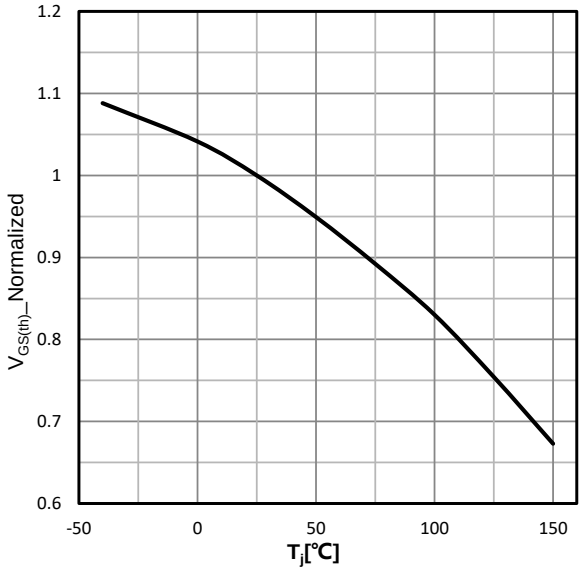
$I_D=f(V_{GS})$, $|V_{DS}|>2|I_D|R_{DS}(on)max$;

Figure 4: drain-source on resistance



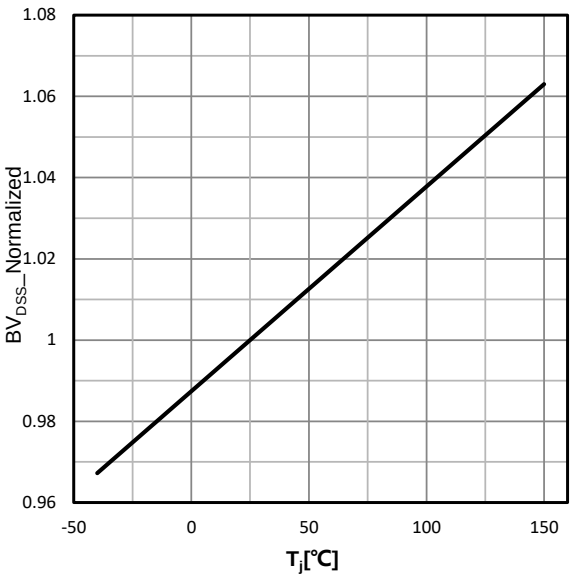
$R_{DS(on)}=f(T_j)$, I_D=-10A, V_{GS}=-10V;

Figure 5: Typ. gate threshold voltage



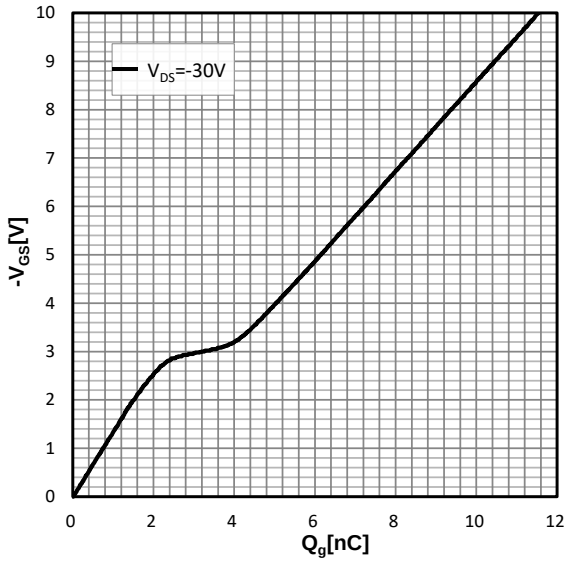
$V_{GS}=f(T_j)$, $V_{GS}=V_{DS}$, I_D=-250μA;

Figure 6: Drain-source breakdown voltage



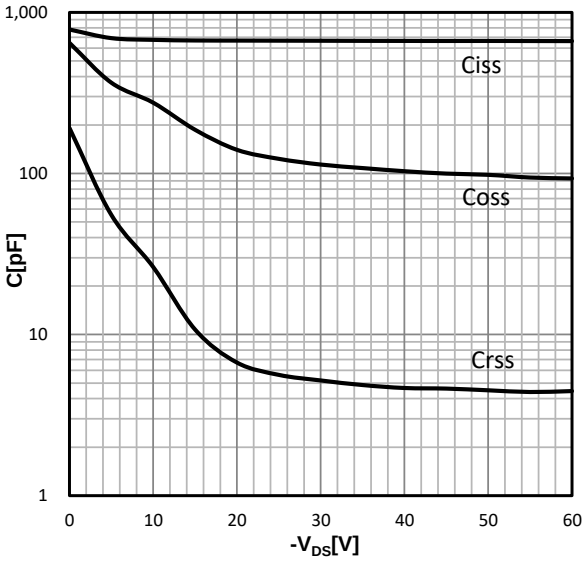
$V_{BR(DSS)}=f(T_j)$; I_D=-250μA;

Figure 7: Typ. gate charge



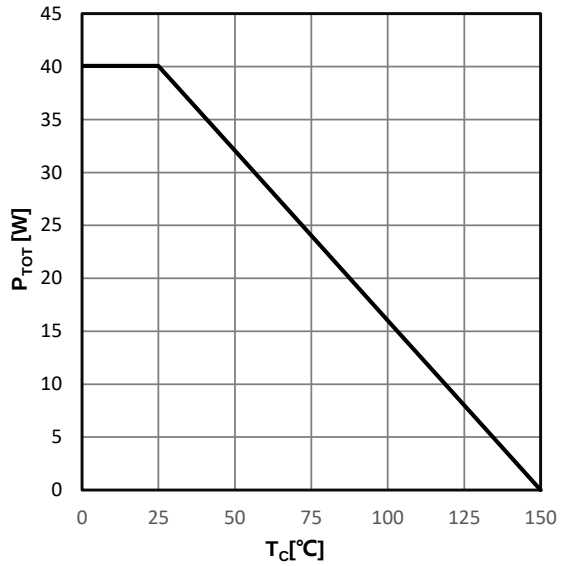
$V_{GS}=f(Q_g)$, I_D=-10A, T_j=25 °C; parameter: V_{DS}

Figure 8: Typ. Capacitances



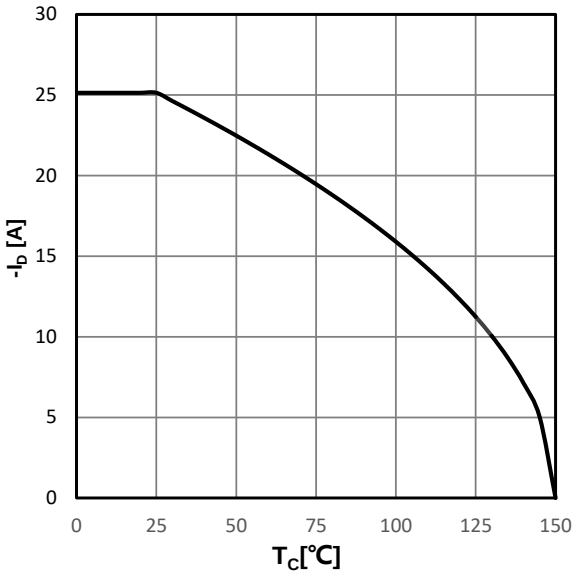
C=f(V_{DS}); V_{GS}=0V; f=1.0 MHz;

Figure 9: Power dissipation



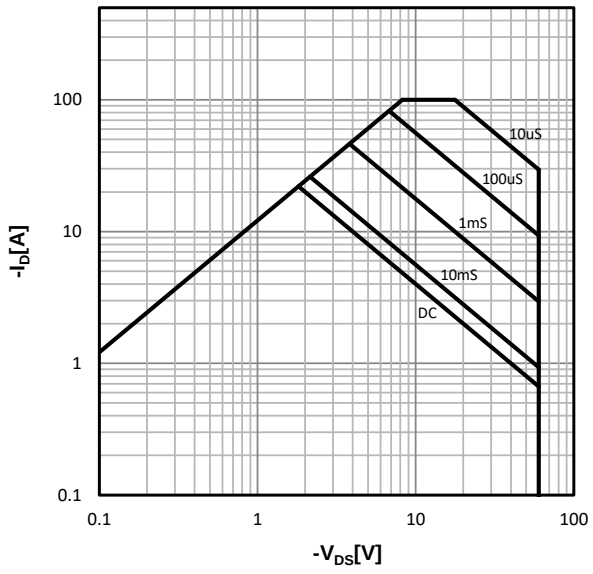
$P_{tot}=f(T_C)$;

Figure 10:Drain current



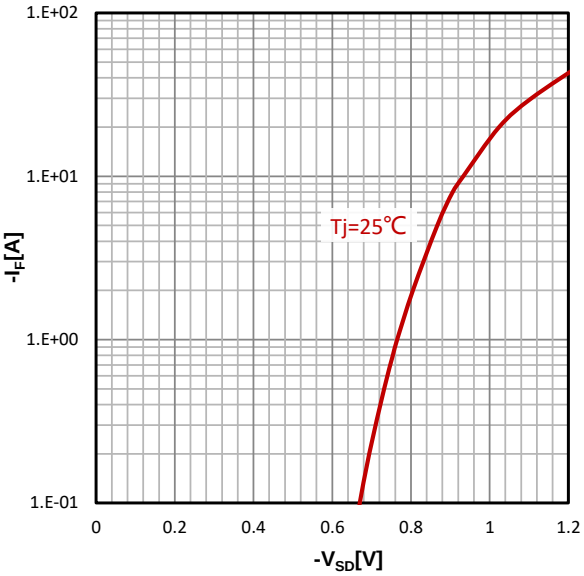
$I_D=f(T_C)$;

Figure 11: Safe operating area



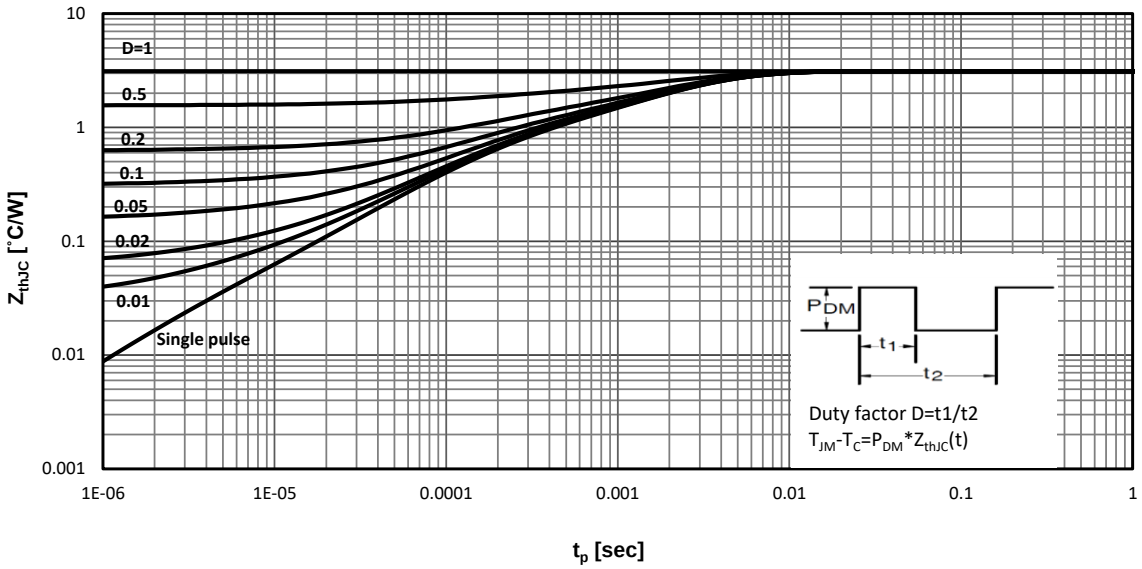
$I_D=f(V_{DS})$; $T_C=25$ °C; D=0; parameter: tp

Figure 12: Typ. forward characteristics



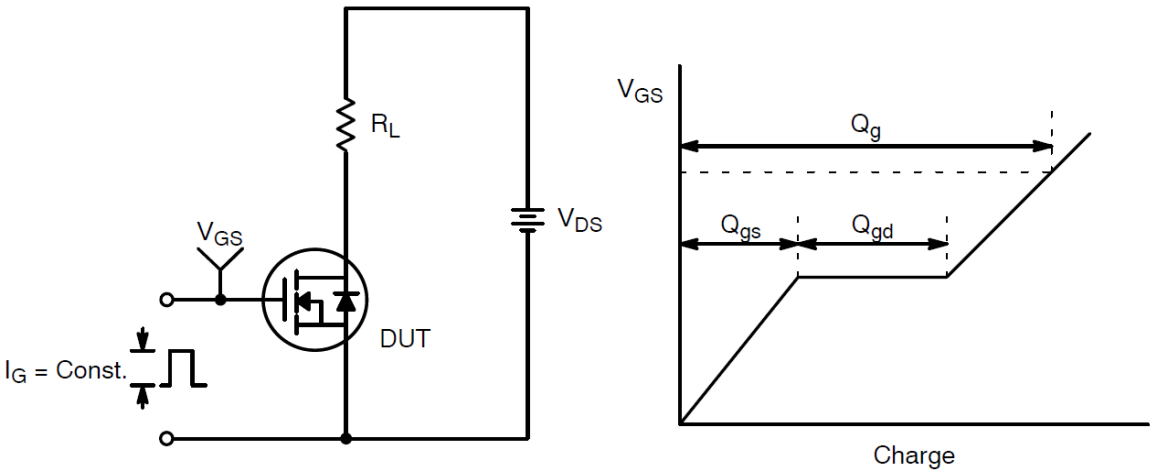
$I_F=f(V_{SD})$;

Figure 13: Max. Transient Thermal Impedance

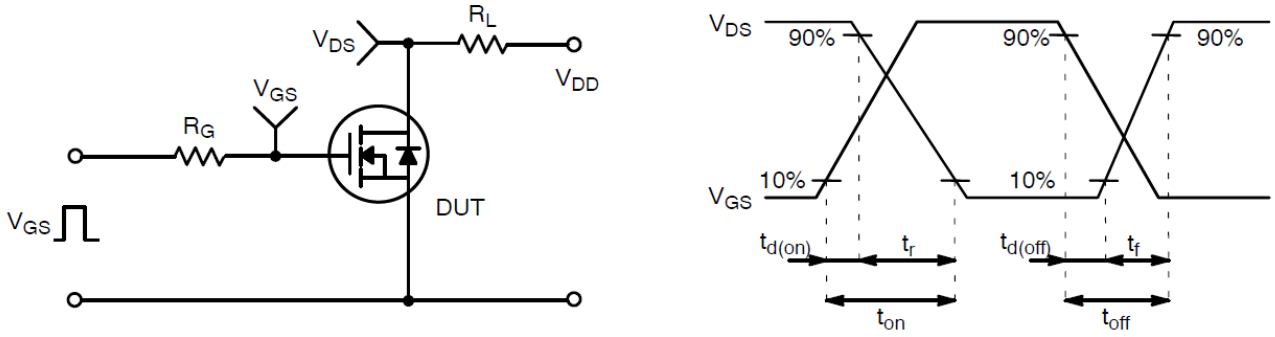


$Z_{thJC}=f(t_p)$; parameter: D

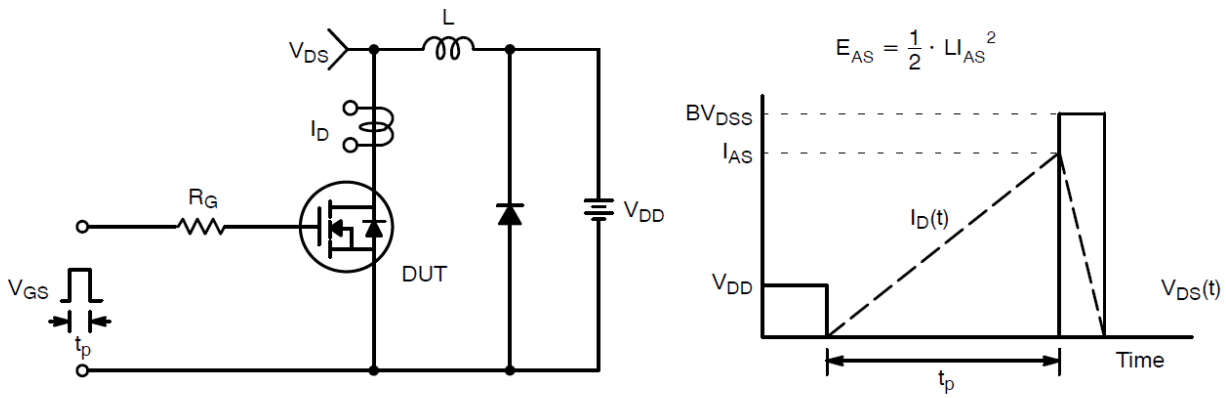
Test Circuit and Waveform:



Gate Charge Test Circuit & Waveform

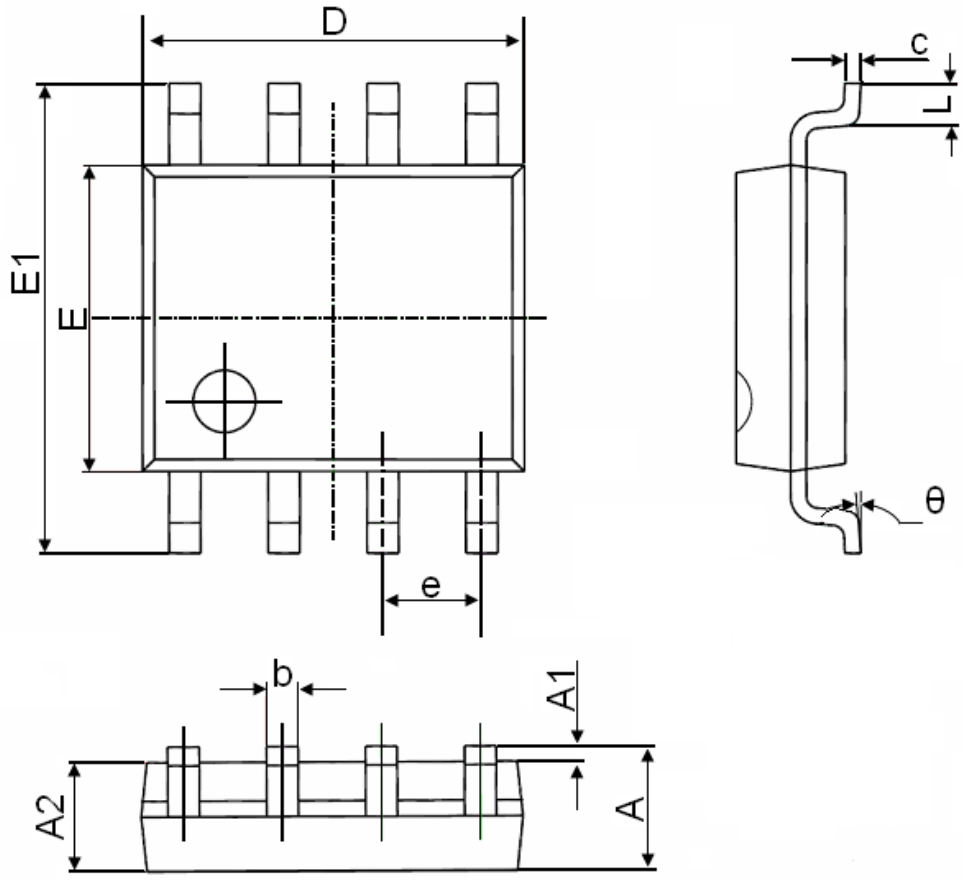


Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms

Package Mechanical Data- SOP8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°